

I) IC Lab Schedule (2009 Spring PRISM)

DATE	LAB	DESCRIPTION
February 05		No Lab
February 12	1	Lab tour; Safety discussion; Determining charge carrier type; Determining resistivity.
February 19	2	Wafer clean; Wet oxidation.
February 26	3	Photolithography Level 1; Oxide etch; Strip resist; Wafer clean; Spin on dopant glass.
March 05	4	Diffuse; Etch dopant glass; Demonstrate diode electrical characteristics.
March 12	5	Photolithography Level 2; Oxide etch; Strip resist; Wafer clean; Gate oxidation
March 19		Spring Break
March 26	6	Photolithography Level 3; Oxide etch; Strip resist; Photolithography Level 4.
April 02	7	Evaporate aluminum; Lift-off; Sinter & Anneal; Solder to glass slide
April 09	8	Measurement Experiments 1-6.
April 16	9	Measurement Experiments 1-6.
April 23	10	Measurement Experiments 1-6.
April 29	11	Measurement Experiments 1-6.
May 07		Reading Period